

AMENDMENTS TO THE ABSTRACT

Please replace the paragraph beginning at page 30, line 2, with the following rewritten paragraph:

-- A film carrier tape for mounting an electronic part of the present invention ~~is~~ includes a film carrier tape comprising ~~a long~~ an elongated insulating film and ~~a large number~~ having a plurality of wiring patterns formed on a surface of the insulating film, said ~~the~~ wiring patterns being made of a conductive metal, wherein the wiring patterns are each independently covered with a solder resist layer except a connecting terminal portion, and the solder resist layer formed on each surface of the wiring patterns is ~~split and/or~~ divided into plural sections. ~~According to the present invention, warpage~~ Warpage distortion that ~~heretofore~~ occurs on each of a plural film carriers arranged, such as CSP, COF and BGA, provided in a film carrier tape for mounting an electronic part in the width direction of the tape can be reduced. --